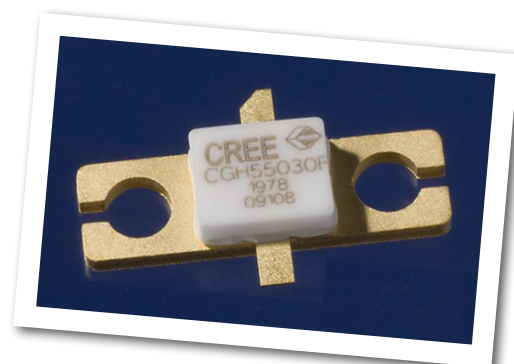


# CGH55030F

**30 W, 5500-5800 MHz, 28V, GaN HEMT for WiMAX**

Cree's CGH55030F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH55030F ideal for 5.5-5.8 GHz WiMAX and BWA amplifier applications. The transistor is supplied in a ceramic/metal flange package. Based on appropriate external match adjustment, the CGH55030F is suitable for 4.9 - 5.5 GHz applications as well.



Package Type: 440166  
PN: CGH55030F

## Typical Performance Over 5.5-5.8GHz ( $T_c = 25^\circ\text{C}$ ) of Demonstration Amplifier

Parameter	5.50 GHz	5.65 GHz	5.80 GHz	Units
Small Signal Gain	9.5	10.0	9.5	dB
EVM at $P_{AVE} = 29\text{ dBm}$	1.1	0.9	0.9	%
EVM at $P_{AVE} = 36\text{ dBm}$	2.2	1.4	1.4	%
Drain Efficiency at $P_{AVE} = 4\text{ W}$	23	24	25	%
Input Return Loss	10.8	22	9.3	dB

### Note:

Measured in the CGH55030F-TB amplifier circuit, under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

## Features

- 300 MHz Instantaneous Bandwidth
- 30 W Peak Power Capability
- 10 dB Small Signal Gain
- 4 W  $P_{AVE} < 2.0\%$  EVM
- 25 % Efficiency at 4 W Average Power
- Designed for WiMAX Fixed Access 802.16-2004 OFDM Applications
- Designed for Multi-carrier DOCSIS Applications



Large Signal Models Available for SiC & GaN

## Absolute Maximum Ratings (not simultaneous) at 25 °C Case Temperature

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	84	Volts
Gate-to-Source Voltage	$V_{GS}$	-10, +2	Volts
Power Dissipation	$P_{DISS}$	14	Watts
Storage Temperature	$T_{STG}$	-55, +150	°C
Operating Junction Temperature	$T_J$	225	°C
Maximum Forward Gate Current	$I_{GMAX}$	7.0	mA
Soldering Temperature <sup>1</sup>	$T_S$	245	°C
Screw Torque	$\tau$	60	in-oz
Thermal Resistance, Junction to Case <sup>2</sup>	$R_{\theta JC}$	4.8	°C/W
Case Operating Temperature <sup>2</sup>	$T_C$	-40, +105	°C

Note:

<sup>1</sup> Refer to the Application Note on soldering at [www.cree.com/products/wireless\\_apnotes.asp](http://www.cree.com/products/wireless_apnotes.asp)

<sup>2</sup> Measured for the CGH55030F at  $P_{DISS} = 14$  W

## Electrical Characteristics ( $T_C = 25^\circ\text{C}$ )

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.3	-2.3	VDC	$V_{DS} = 10$ V, $I_D = 7.2$ mA
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-3.0	-	VDC	$V_{DS} = 28$ V, $I_D = 250$ mA
Saturated Drain Current	$I_{DS}$	5.8	7.0	-	A	$V_{DS} = 6.0$ V, $V_{GS} = 2$ V
Drain-Source Breakdown Voltage	$V_{BR}$	84	100	-	VDC	$V_{GS} = -8$ V, $I_D = 7.2$ mA
<b>RF Characteristics<sup>2,3</sup> (<math>T_C = 25^\circ\text{C}</math>, <math>F_0 = 5.65</math> GHz unless otherwise noted)</b>						
Small Signal Gain	$G_{SS}$	8.5	10.0	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 250$ mA
Drain Efficiency <sup>4</sup>	$\eta$	19	24	-	%	$V_{DD} = 28$ V, $I_{DQ} = 250$ mA, $P_{AVE} = 4$ W
Back-Off Error Vector Magnitude	$EVM_1$	-	2.5	-	%	$V_{DD} = 28$ V, $I_{DQ} = 250$ mA, $P_{AVE} = 29$ dBm
Error Vector Magnitude	$EVM_2$	-	2.0	-		$V_{DD} = 28$ V, $I_{DQ} = 250$ mA, $P_{AVE} = 4$ W
Output Mismatch Stress	VSWR	-	10:1	-	$\Psi$	No damage at all phase angles, $V_{DD} = 28$ V, $I_{DQ} = 250$ mA, $P_{AVE} = 4$ W
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{GS}$	-	9.3	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz
Output Capacitance	$C_{DS}$	-	2.0	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz
Feedback Capacitance	$C_{GD}$	-	0.9	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz

Notes:

<sup>1</sup> Measured on wafer prior to packaging.

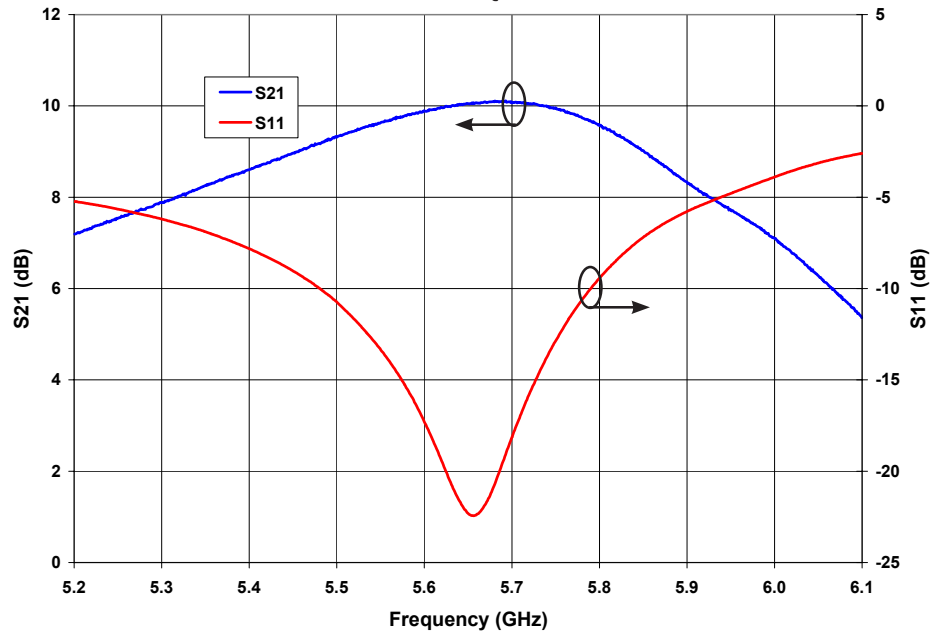
<sup>2</sup> Measured in the CGH55030F-TB test fixture.

<sup>3</sup> Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

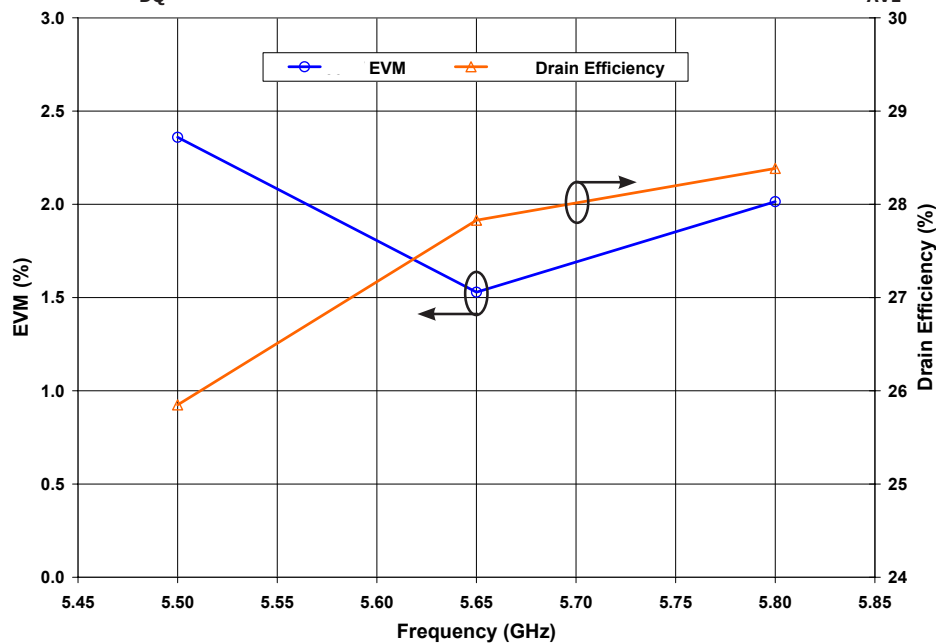
<sup>4</sup> Drain Efficiency =  $P_{OUT} / P_{DC}$

## Typical WiMAX Performance

**Small Signal S-Parameters vs Frequency of CGH55030F in the CGH55030F-TB**  
 $V_{DD} = 28 \text{ V}$ ,  $I_{DQ} = 250 \text{ mA}$



**Typical EVM and Efficiency versus Frequency of CGH55030F in the CGH55030F-TB**  
 $V_{DD} = 28 \text{ V}$ ,  $I_{DQ} = 250 \text{ mA}$ , 802.16-2004 OFDM, PAR=9.8 dB,  $P_{AVE} = 5 \text{ W}$

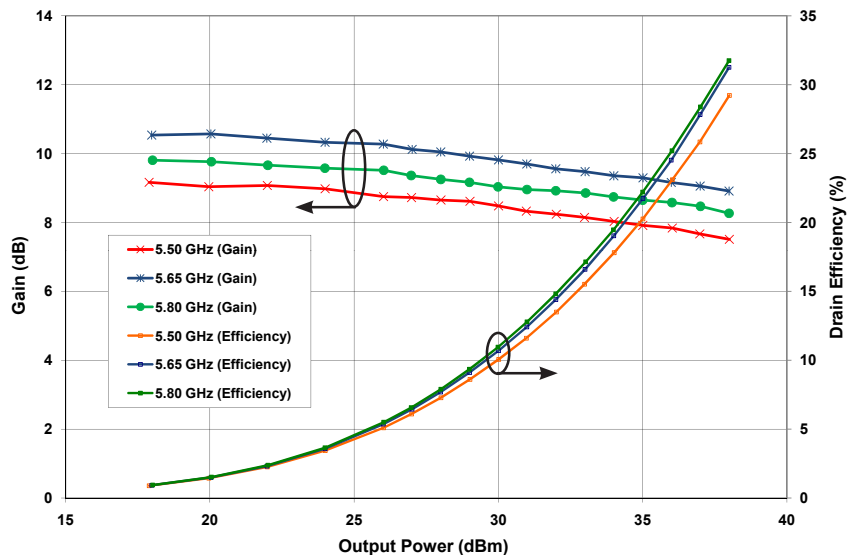


Note:

Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

## Typical WiMAX Performance

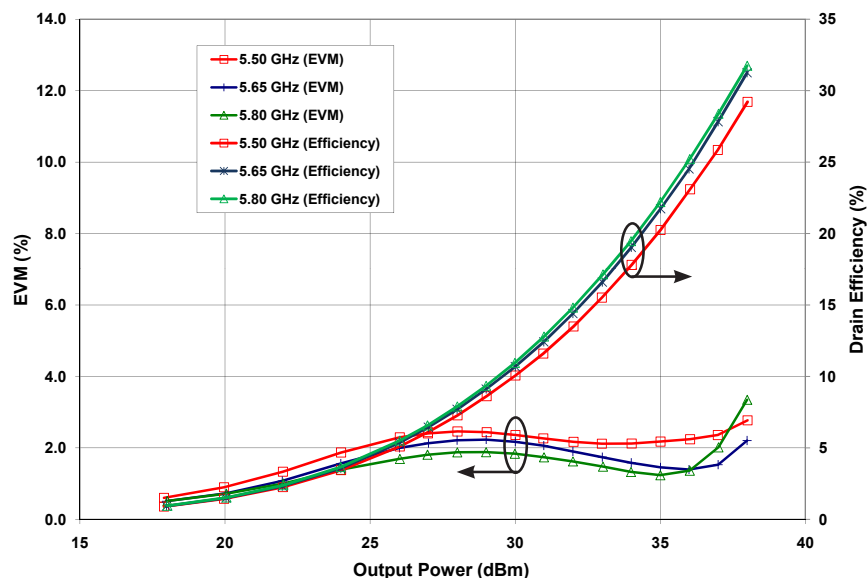
### Drain Efficiency and Gain vs Output Power of CGH55030F in CGH55030F-TB $V_{DD} = 28\text{ V}$ , $I_{DQ} = 250\text{ mA}$ , 802.16-2004 OFDM, PAR=9.8 dB



Note:

Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

### Typical EVM and Drain Efficiency vs Output Power of CGH55030F in CGH55030F-TB at 5.50GHz, 5.65 GHz, 5.80GHz, 802.16-2004 OFDM, PAR=9.8 dB

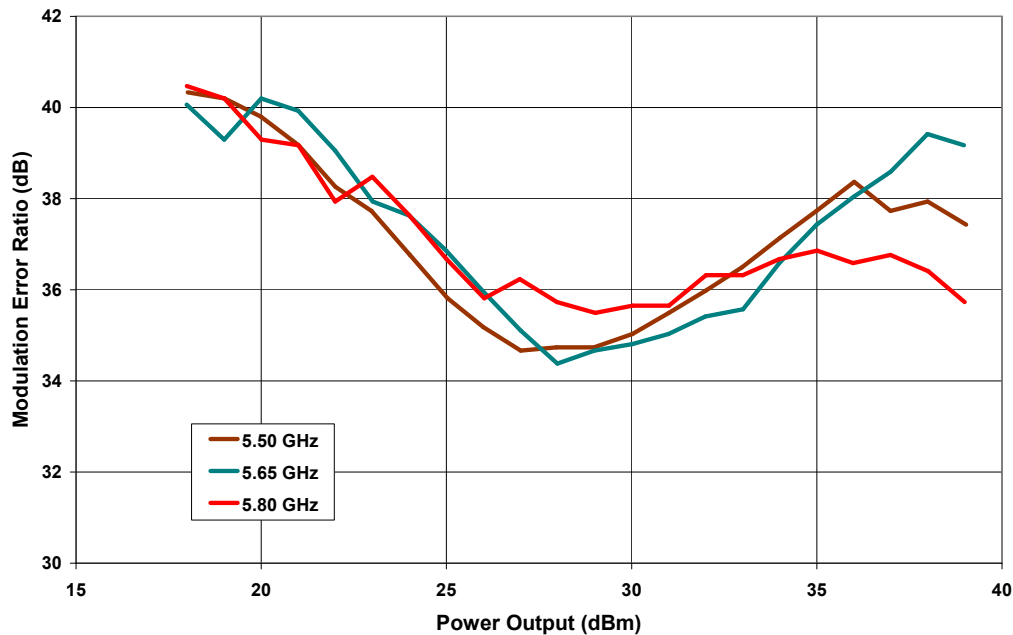


Note:

Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

## Typical DOCSIS Performance

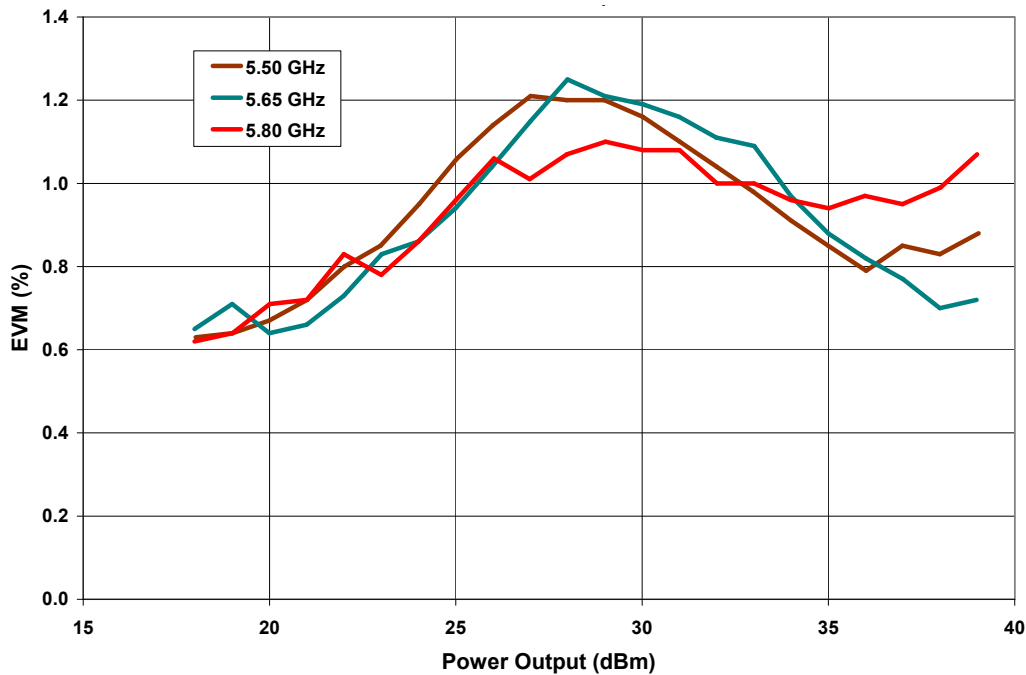
**Modulation Error Ratio vs Power Output of CGH55030F in Broadband Amplifier Circuit**



Note:

MER is the metric of choice for cable systems and can be related to EVM by the following equation:  $EVM(\%) = 100 \times 10^{-((MER_{dB} + MTAdB)/20)}$ . MTA is the "maximum-to-average constellation power ratio" which varies with the modulation type: MTA = 0 for BPSK and QPSK; 2.55 for 16QAM and 8QAM-DS; 3.68 for 64QAM and 32QAM-DS; 4.23 for 256QAM and 128QAM-DS

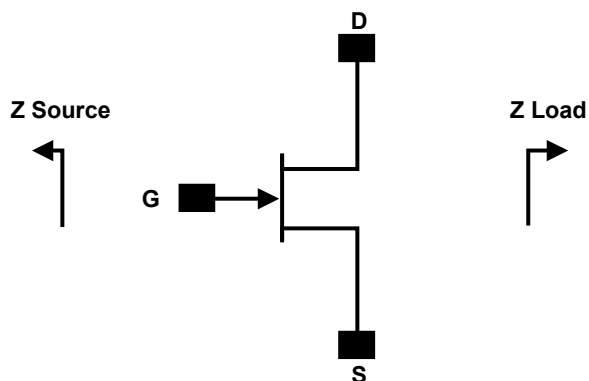
**EVM vs Output Power of CGH55030F in Broadband Amplifier Circuit**



Note:

Under DOCSIS, 6.0 MHz Channel BW, 64 QAM, PN23, Filter Alpha 0.18, PAR = 6.7dB.

## Source and Load Impedances



Frequency (MHz)	Z Source	Z Load
5500	8.0 - j12.4	13.2 - j12.2
5650	8.7 - j13.1	13.8 - j11.4
5800	8.4 - j14.0	14.4 - j10.7

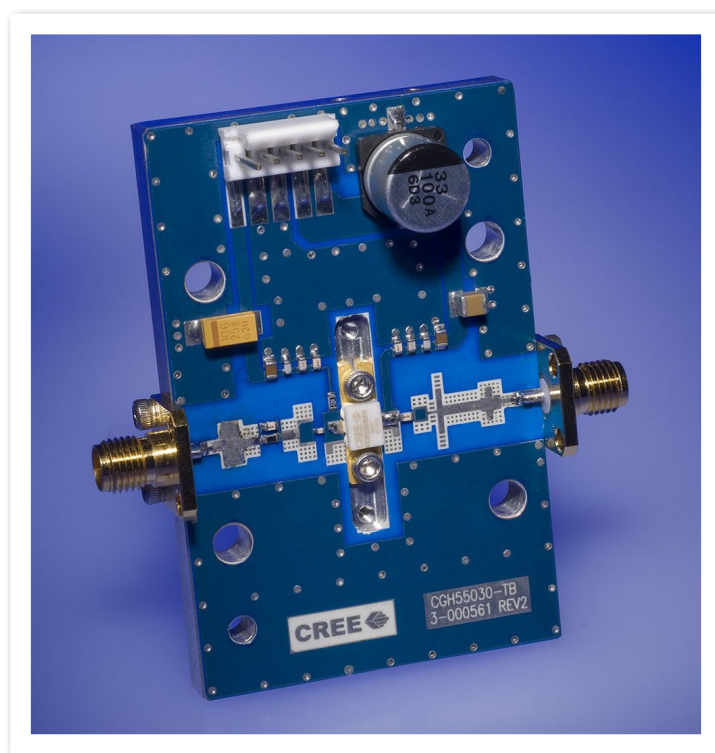
Note 1.  $V_{DD} = 28V$ ,  $I_{DQ} = 250$  mA in the 440166 package.

Note 2. Impedances are extracted from the CGH55030F-TB demonstration amplifier and are not source and load pull data derived from the transistor.

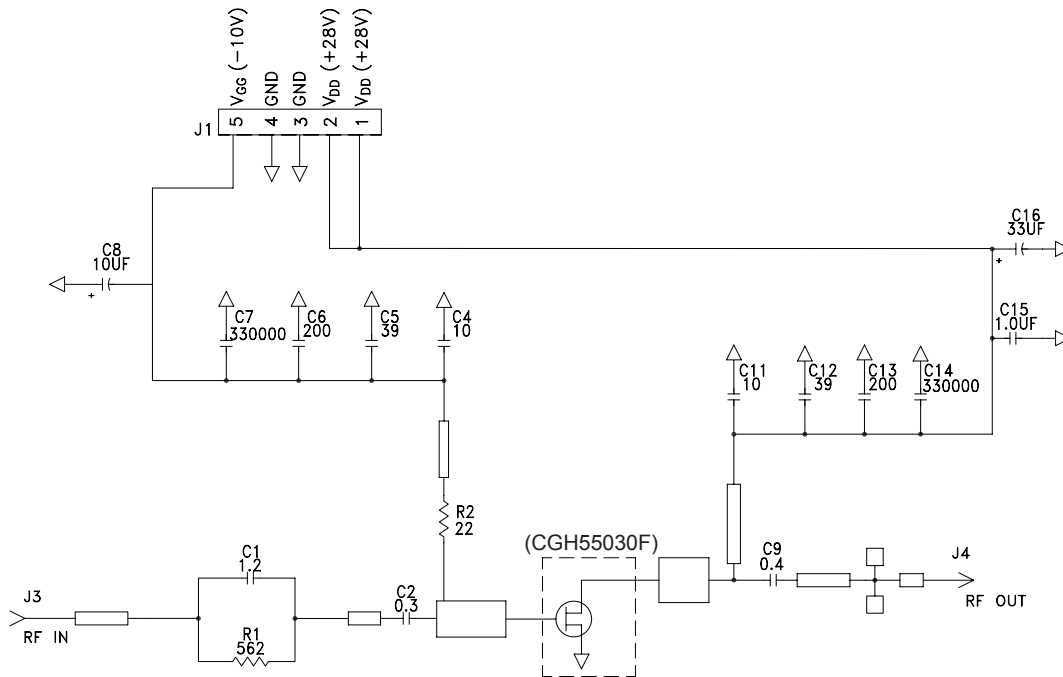
## CGH55030F-TB Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 1/16W, 0603, 1%, 562 OHMS	1
R2	RES, 1/16W, 0603, 1%, 22.6 OHMS	1
C2	CAP, 0.3pF, +/-0.05pF, 0402, ATC600L	1
C16	CAP, 33 UF, 20%, G CASE	1
C15	CAP, 1.0UF, 100V, 10%, X7R, 1210	1
C8	CAP 10UF 16V TANTALUM	1
C9	CAP, 0.4pF, +/-0.05pF, 0603, ATC600S	1
C1	CAP, 1.2pF, +/-0.1pF, 0603, ATC600S	1
C6,C13	CAP,200 PF,0603 PKG, 100 V	2
C4,C11	CAP, 10.0pF,+/-5%, 0603, ATC600S	2
C5,C12	CAP, 39pF, +/-5%, 0603, ATC600S	2
C7,C14	CAP, 330000PF, 0805, 100V, TEMP STABILIZ	2
J3,J4	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
J1	HEADER RT>PLZ .1CEN LK 5POS	1
-	PCB, RO4350B, Er = 3.48, h = 20 mil	1
-	CGH55030F	1

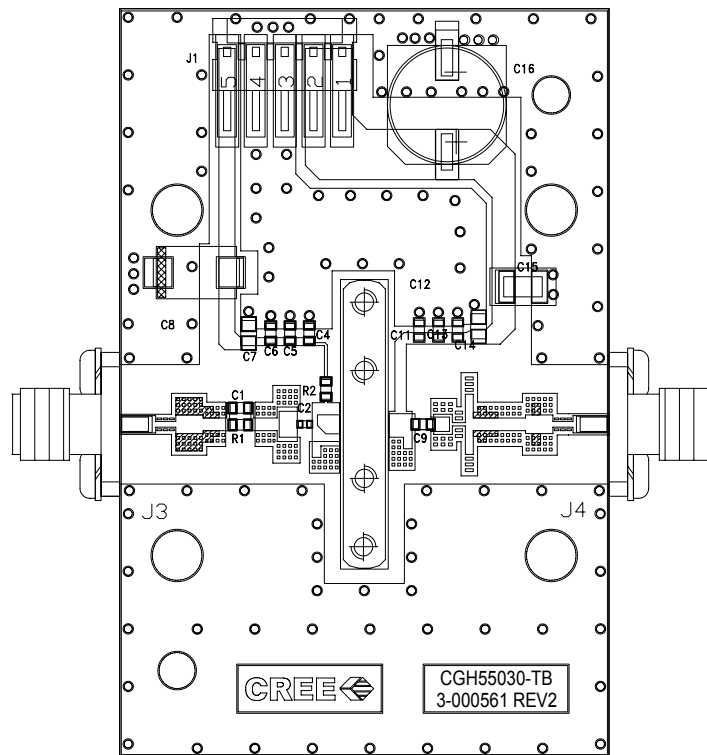
## CGH55030F-TB Demonstration Amplifier Circuit



## CGH55030F-TB Demonstration Amplifier Circuit Schematic



## CGH55030F-TB Demonstration Amplifier Circuit Outline





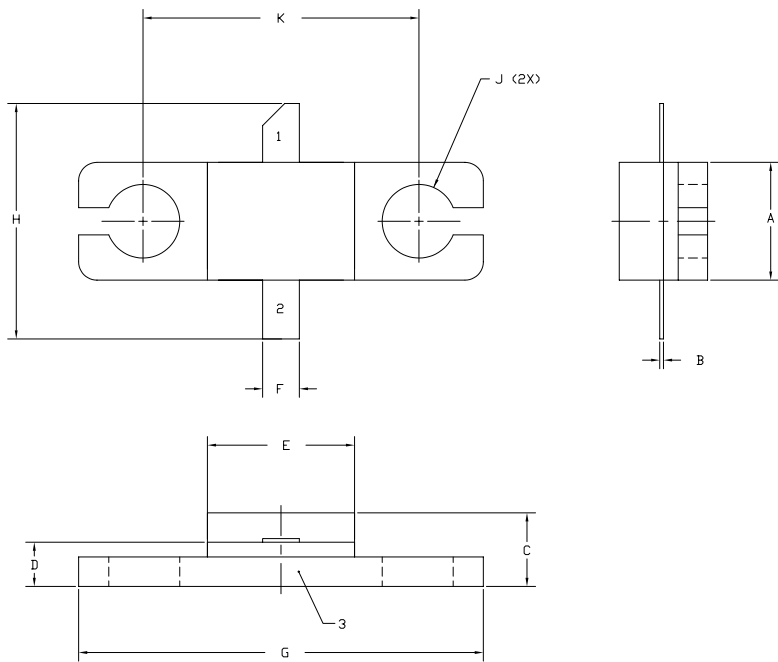


# Typical Package S-Parameters for CGH55030F (Small Signal, $V_{DS} = 28\text{ V}$ , $I_{DQ} = 250\text{ mA}$ , angle in degrees)

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.914	-163.42	12.17	89.92	0.021	5.48	0.528	-163.71
600 MHz	0.914	-167.32	10.17	86.47	0.021	3.15	0.531	-166.13
700 MHz	0.914	-170.31	8.73	83.46	0.021	1.28	0.534	-167.86
800 MHz	0.913	-172.73	7.65	80.72	0.021	-0.30	0.537	-169.14
900 MHz	0.913	-174.76	6.80	78.18	0.021	-1.68	0.540	-170.15
1.0 GHz	0.914	-176.53	6.11	75.78	0.021	-2.91	0.544	-170.97
1.1 GHz	0.914	-178.09	5.55	73.47	0.021	-4.03	0.547	-171.66
1.2 GHz	0.914	-179.52	5.08	71.24	0.021	-5.04	0.551	-172.26
1.3 GHz	0.914	179.17	4.69	69.08	0.020	-5.98	0.555	-172.80
1.4 GHz	0.915	177.95	4.35	66.96	0.020	-6.84	0.559	-173.30
1.5 GHz	0.915	176.79	4.05	64.89	0.020	-7.63	0.563	-173.77
1.6 GHz	0.915	175.68	3.79	62.86	0.020	-8.37	0.567	-174.23
1.7 GHz	0.916	174.62	3.56	60.85	0.020	-9.04	0.571	-174.68
1.8 GHz	0.916	173.60	3.36	58.88	0.020	-9.66	0.576	-175.13
1.9 GHz	0.916	172.60	3.18	56.93	0.019	-10.22	0.580	-175.59
2.0 GHz	0.917	171.62	3.01	55.00	0.019	-10.72	0.585	-176.05
2.1 GHz	0.917	170.67	2.86	53.09	0.019	-11.16	0.590	-176.52
2.2 GHz	0.918	169.72	2.73	51.21	0.019	-11.54	0.595	-177.01
2.3 GHz	0.918	168.79	2.60	49.34	0.019	-11.87	0.599	-177.51
2.4 GHz	0.919	167.87	2.49	47.49	0.018	-12.13	0.604	-178.03
2.5 GHz	0.919	166.95	2.39	45.66	0.018	-12.33	0.609	-178.56
2.6 GHz	0.919	166.04	2.29	43.84	0.018	-12.46	0.614	-179.11
2.7 GHz	0.920	165.13	2.20	42.03	0.018	-12.53	0.619	-179.68
2.8 GHz	0.920	164.22	2.12	40.24	0.017	-12.53	0.623	179.74
2.9 GHz	0.921	163.31	2.04	38.47	0.017	-12.46	0.628	179.13
3.0 GHz	0.921	162.41	1.97	36.70	0.017	-12.32	0.633	178.51
3.2 GHz	0.922	160.58	1.85	33.21	0.017	-11.83	0.642	177.22
3.4 GHz	0.923	158.73	1.73	29.76	0.016	-11.04	0.650	175.85
3.6 GHz	0.923	156.87	1.63	26.34	0.016	-9.97	0.659	174.42
3.8 GHz	0.924	154.97	1.55	22.96	0.016	-8.61	0.666	172.93
4.0 GHz	0.924	153.04	1.47	19.61	0.016	-7.01	0.674	171.37
4.2 GHz	0.925	151.06	1.40	16.29	0.016	-5.19	0.681	169.74
4.4 GHz	0.925	149.04	1.34	12.98	0.016	-3.21	0.688	168.06
4.6 GHz	0.925	146.97	1.28	9.68	0.016	-1.14	0.694	166.32
4.8 GHz	0.926	144.85	1.23	6.39	0.016	0.95	0.699	164.51
5.0 GHz	0.926	142.66	1.19	3.11	0.017	2.98	0.705	162.64
5.2 GHz	0.926	140.41	1.15	-0.18	0.018	4.88	0.709	160.70
5.4 GHz	0.926	138.08	1.11	-3.48	0.018	6.58	0.714	158.70
5.6 GHz	0.925	135.68	1.08	-6.79	0.019	8.03	0.717	156.63
5.8 GHz	0.925	133.19	1.05	-10.13	0.020	9.19	0.721	154.49
6.0 GHz	0.925	130.62	1.02	-13.50	0.022	10.03	0.724	152.27

Download this s-parameter file in ".s2p" format at [http://www.cree.com/products/wireless\\_s-parameters.asp](http://www.cree.com/products/wireless_s-parameters.asp)

# Product Dimensions CGH55030F (Package Type — 440166)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
  4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
  5. ALL PLATED SURFACES ARE Ni/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.155	0.165	3.94	4.19
B	0.004	0.006	0.10	0.15
C	0.115	0.135	2.92	3.43
D	0.057	0.067	1.45	1.70
E	0.195	0.205	4.95	5.21
F	0.045	0.055	1.14	1.40
G	0.545	0.555	13.84	14.09
H	0.280	0.360	7.87	8.38
J	ø .100		2.54	
K	0.375		9.53	

PIN 1. GATE  
PIN 2. DRAIN  
PIN 3. SOURCE



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